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| INFORMATION DISCLOSURE CITATION <i>(Use several sheets if necessary)</i> | Docket Number (Optional) END919980110 | Application Number |
| | Applicant(s) Jimarez et al. | |
| | Filing Date | Group Art Unit |

09/18/01
 02/13/01
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| *EXAMINER INITIAL | REF | DOCUMENT NUMBER | DATE | NAME | CLASS | SUBCLASS | FILED DATE IF APPROPRIATE |
| NB | | 4,376,505 | 3/1983 | Wojcik | | | |
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| | REF | DOCUMENT NUMBER | DATE | COUNTRY | CLASS | SUBCLASS | Translation | |
| | | | | | | | YES | NO |
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| NB | | IBM Technical Disclosure Bulletin, Vol. 32, No. 10B, March 1990, ENCAPSULATED SOLDER JOINT FOR CHIP MOUNTING, page 480. |
| NB | | IBM Technical Disclosure Bulletin, Vol. 32, No. 6A, November 1989, IMPROVED C4 RELIABILITY USING LOW MODULUS DIELECTRIC LAYER, pages 315-316. |

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| EXAMINER Nema Berezny | DATE CONSIDERED 5-15-02 |
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INFORMATION DISCLOSURE CITATION

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Applicant(s)

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EXAMINER

Nema Berezny

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